



MS2552

RF & MICROWAVE TRANSISTORS

PRODUCT PREVIEW

DESCRIPTION

The MS2552 device is a high power pulsed transistor specifically designed for DME/TACAN avionics applications.

This device is capable of withstanding an infinite load VSWR at any phase angle under full rated conditions. Low RF thermal resistance and semi-automatic bonding techniques ensure high reliability and product consistency.

The MS2552 is housed in the industry-standard AMPAC™ metal/ceramic hermetic package with internal input/output matching structures.

IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

KEY FEATURES

- Refractory/Gold Metallization
- Emitter Ballasted
- Ruggedized VSWR ∞ :1 Capability
- Input/Output Matching
- Overlay Geometry
- Metal/Ceramic Hermetic Package
- P_{OUT} = 325 W Min.
- G_p = 6.7 dB Gain

APPLICATIONS/BENEFITS

- Avionics Applications

ABSOLUTE MAXIMUM RATINGS (T_{CASE} = 25°C)

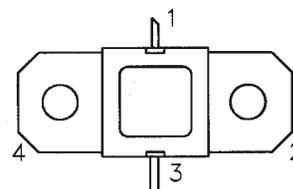
| Symbol | Parameter | Value | Unit |
|-------------------|---|-------------|------|
| P _{DISS} | Power Dissipation* (T _C ≤ 100°C) | 880 | W |
| I _C | Device Current* | 24 | A |
| V _{CC} | Collector-Supply Voltage* | 55 | V |
| T _J | Junction Temperature (Pulsed RF Operation) | 250 | °C |
| T _{STG} | Storage Temperature | -65 to +150 | °C |

THERMAL DATA

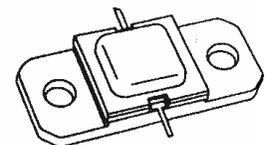
| | | | |
|----------------------|----------------------------------|------|------|
| R _{TH(j-c)} | Junction-Case Thermal Resistance | 0.17 | °C/W |
|----------------------|----------------------------------|------|------|

Applies only to rated RF amplifier operation

PIN CONNECTION



- 1. Collector
- 2. Base
- 3. Emitter
- 4. Base



.400 x .400 2NLFL (S042)
hermetically sealed





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STATIC ELECTRICAL SPECIFICATIONS (T_{CASE} = 25°C)

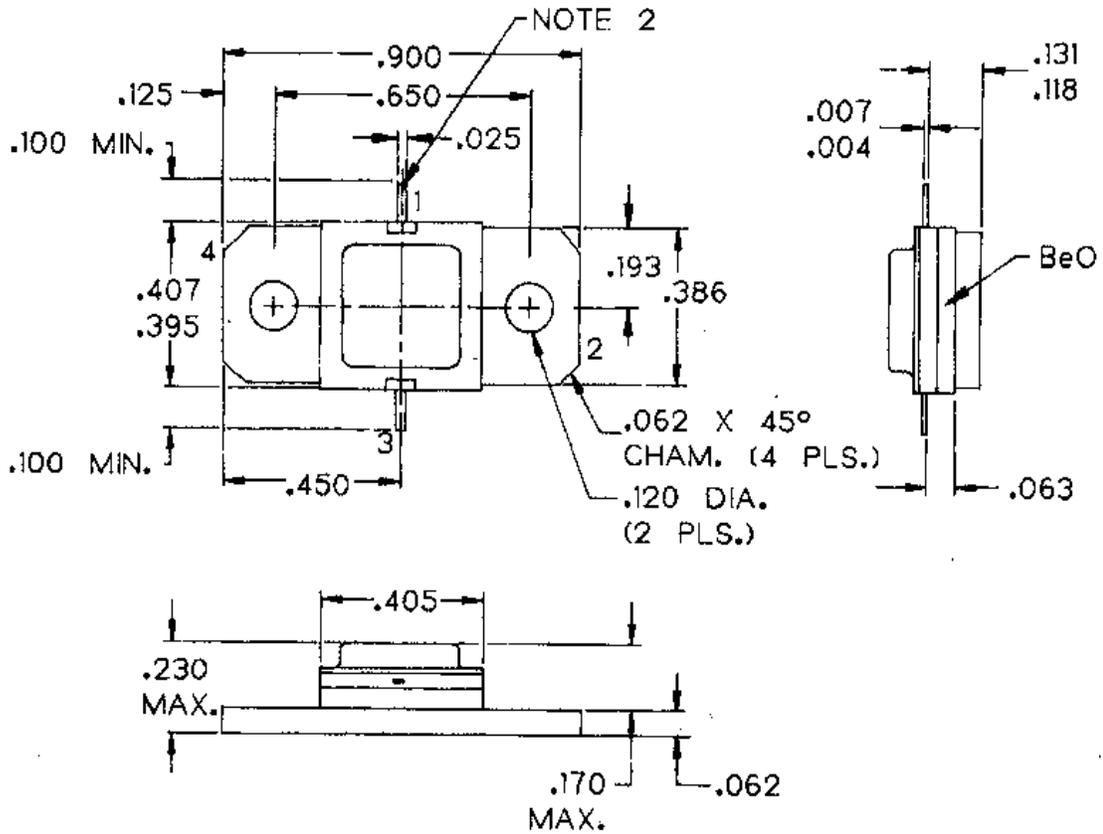
| Symbol | Test Conditions | | MS2552 | | | Units |
|-------------------------|------------------------------|------------------------------|--------|------|------|-------|
| | | | Min. | Typ. | Max. | |
| BV_{CBO} | I_C = 10 mA | I_E = 0 mA | 65 | — | — | V |
| BV_{EBO} | I_E = 1 mA | I_C = 0 V | 3.5 | — | — | V |
| BV_{CER} | I_C = 25 mA | R_{BE} = 10 Ω | 65 | — | — | V |
| I_{CES} | V_{BE} = 0 V | v_{CE} = 50 V | — | — | 25 | mA |
| h_{FE} | V_{CE} = 5 V | I_C = 1 A | 15 | — | 120 | — |

DYMANIC ELECTRICAL SPECIFICATIONS (T_{CASE} = 25°C)

| Symbol | Test Conditions | | | MS2575 | | | Units |
|------------------------|----------------------------|------------------------------|------------------------------|--------|------|------|-------|
| | | | | Min. | Typ. | Max. | |
| P_{OUT} | f = 1025 – 1150 MHz | P_{IN} = 70 W | V_{CC} = 50 V | 325 | 360 | — | W |
| η_c | f = 1025 – 1150 MHz | P_{IN} = 70 W | V_{CC} = 50 V | 40 | 41 | — | % |
| G_P | f = 1025 – 1150 MHz | P_{IN} = 70 W | V_{CC} = 50 V | 6.7 | 7.1 | — | dB |

Note: Pulse width = 10μSec
Duty Cycle = 1%

Ref.: Dwg. No.: J113214F



NOTES:

1. ALL TOLERANCE $\pm .010$ EXCEPT WHERE NOTED;
DIMENSIONS IN INCHES.
2. COLLECTOR LEAD SLANT CUT.



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www.Microsemi.com

NOTES